FAIRCHILD
SEMICONDUCTOR™

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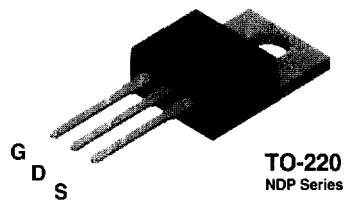
NDP708A / NDP708AE / NDP708B / NDP708BE
NDB708A / NDB708AE / NDB708B / NDB708BE
N-Channel Enhancement Mode Field Effect Transistor

General Description

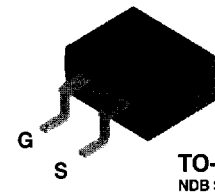
These N-channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation modes. These devices are particularly suited for low voltage applications such as automotive, DC/DC converters, PWM motor controls, and other battery powered circuits where fast switching, low in-line power loss, and resistance to transients are needed.

Features

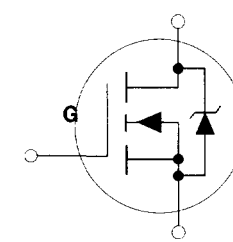
- 60 and 54A, 80V. $R_{DS(ON)}$ = 0.022 and 0.025Ω.
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- 175°C maximum junction temperature rating.
- High density cell design (3 million/in^2) for extremely low $R_{DS(ON)}$.
- TO-220 and TO-263 (D^2PAK) package for both through hole and surface mount applications.



TO-220
NDP Series



TO-263AB
NDB Series



Absolute Maximum Ratings

T_C = 25°C unless otherwise noted

Symbol	Parameter	NDP708A NDP708AE NDB708A NDB708AE	NDP708B NDP708BE NDB708B NDB708BE	Units
V_{DSS}	Drain-Source Voltage	80		V
V_{DGR}	Drain-Gate Voltage ($R_{GS} \leq 1$ MΩ)	80		V
V_{GSS}	Gate-Source Voltage - Continuous	±20		V
	- Nonrepetitive ($t_p < 50$ µs)	±40		V
I_D	Drain Current - Continuous	60	54	A
	- Pulsed	180	162	A
P_D	Total Power Dissipation @ T_C = 25°C	150		W
	Derate above 25°C	1		W/°C
T_J,T_{STG}	Operating and Storage Temperature Range	-65 to 175		°C
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	275		°C

Electrical Characteristics (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Type	Min	Typ	Max	Units
DRAIN-SOURCE AVALANCHE RATINGS (Note 1)							
E_{AS}	Single Pulse Drain-Source Avalanche Energy	V_{DD} = 25 V, I_D = 60 A	NDP708AE NDP708BE			600	mJ
I_{AR}	Maximum Drain-Source Avalanche Current		NDB708AE NDB708BE			60	A
OFF CHARACTERISTICS							
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 µA	ALL	80			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 80 V, V_{GS} = 0 V	ALL			250	µA
		T_J = 125°C				1	mA
I_{GSSF}	Gate - Body Leakage, Forward	V_{GS} = 20 V, V_{DS} = 0 V	ALL			100	nA
I_{GSSR}	Gate - Body Leakage, Reverse	V_{GS} = -20 V, V_{DS} = 0 V	ALL			-100	nA
ON CHARACTERISTICS (Note 2)							
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 µA	ALL	2	2.6	4	V
		T_J = 125°C		1.4	1.9	3.6	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS} = 10 V, I_D = 30 A	NDP708A NDP708AE NDB708A		0.016	0.022	Ω
		T_J = 125°C	NDB708AE		0.025	0.04	Ω
		V_{GS} = 10 V, I_D = 27 A	NDP708B NDP708BE NDB708B			0.25	Ω
		T_J = 125°C	NDB708BE			0.044	Ω
$I_{D(on)}$	On-State Drain Current	V_{GS} = 10 V, V_{DS} = 10 V	NDP708A NDP708AE NDB708A NDB708AE	60			A
			NDP708B NDP708BE NDB708B NDB708BE	54			A
g_{FS}	Forward Transconductance	V_{DS} = 10 V, I_D = 30 A	ALL	16	33		S
DYNAMIC CHARACTERISTICS							
C_{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz	ALL		2800	3600	pF
C_{oss}	Output Capacitance		ALL		780	1000	pF
C_{rss}	Reverse Transfer Capacitance		ALL		285	400	pF

Electrical Characteristics (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Type	Min	Typ	Max	Units
SWITCHING CHARACTERISTICS (Note 2)							
$t_{D(ON)}$	Turn - On Delay Time	V_{DD} = 40 V, I_D = 60 A, V_{GS} = 10 V, R_{GEN} = 5 Ω	ALL		15	25	nS
t_r	Turn - On Rise Time		ALL		143	230	nS
$t_{D(OFF)}$	Turn - Off Delay Time		ALL		58	90	nS
t_f	Turn - Off Fall Time		ALL		108	180	nS
Q_g	Total Gate Charge	V_{DS} = 64 V, I_D = 60 A, V_{GS} = 10 V	ALL		94	130	nC
Q_{gs}	Gate-Source Charge		ALL		16		nC
Q_{gd}	Gate-Drain Charge		ALL		51		nC
DRAIN-SOURCE DIODE CHARACTERISTICS							
I_S	Maximum Continuos Drain-Source Diode Forward Current		NDP708A NDP708AE NDB708A NDB708AE			60	A
			NDP708B NDP708BE NDB708B NDB708BE			54	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		NDP708A NDP708AE NDB708A NDB708AE			180	A
			NDP708B NDP708BE NDB708B NDB708BE			162	A
V_{SD} (Note 2)	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 30 A	ALL		0.91	1.3	V
		T_J = 125°C			0.82	1.2	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_S = 60 A, dI_S/dt = 100 A/µs	ALL		98	140	ns
I_{rr}	Reverse Recovery Current		ALL		6.5	10	A
THERMAL CHARACTERISTICS							
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		ALL			1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		ALL			62.5	°C/W

Notes:
1. NDP708A/708B and NDB708A/708B are not rated for operation in avalanche mode.
2. Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2.0%.

Typical Electrical Characteristics

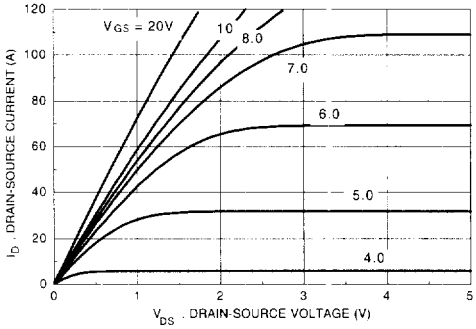


Figure 1. On-Region Characteristics.

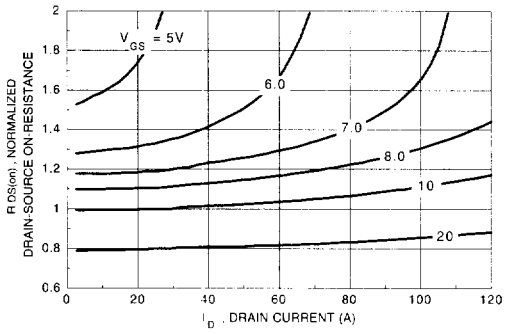


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

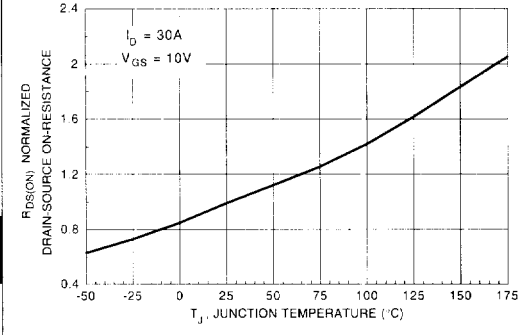


Figure 3. On-Resistance Variation with Temperature.

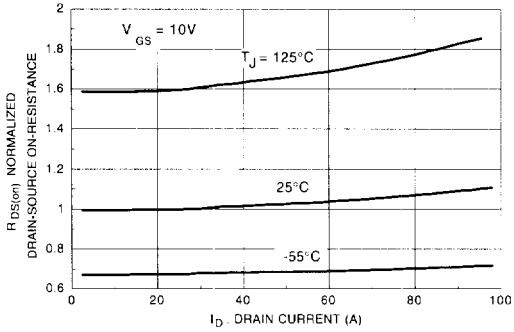


Figure 4. On-Resistance Variation with Drain Current and Temperature.

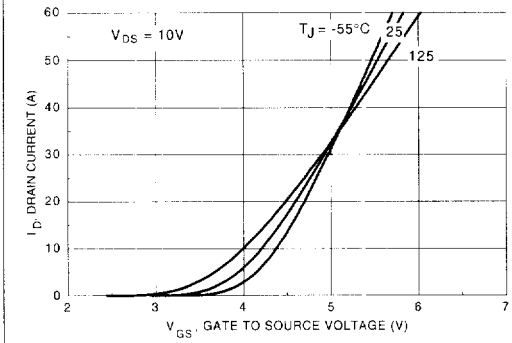


Figure 5. Transfer Characteristics.

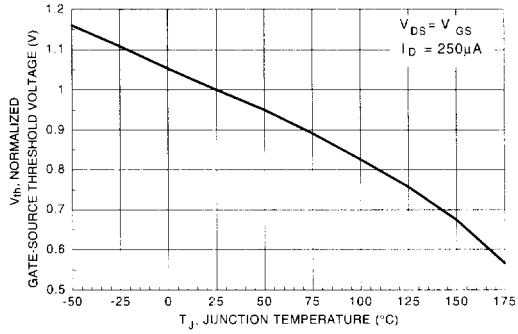


Figure 6. Gate Threshold Variation with Temperature.

Typical Electrical Characteristics (continued)

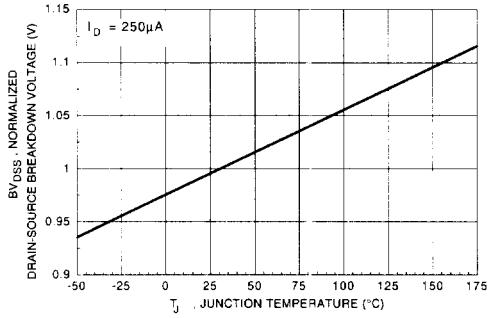


Figure 7. Breakdown Voltage Variation with Temperature.

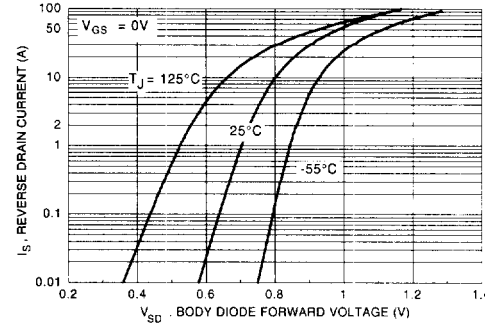


Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.

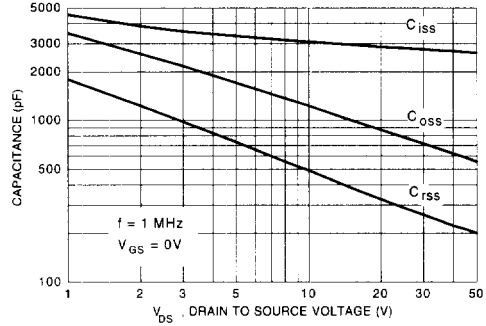


Figure 9. Capacitance Characteristics.

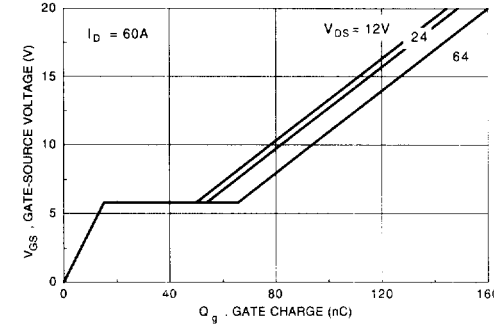


Figure 10. Gate Charge Characteristics.

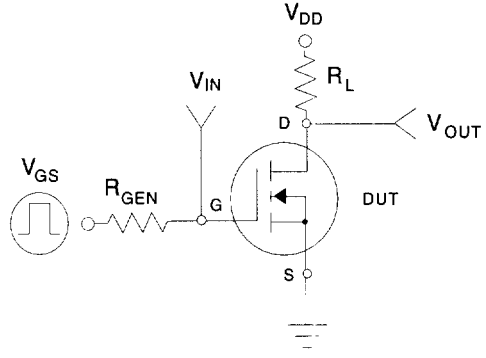


Figure 11. Switching Test Circuit.

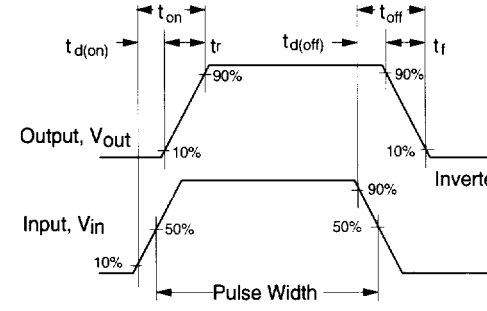


Figure 12. Switching Waveforms.

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Typical Electrical Characteristics (continued)

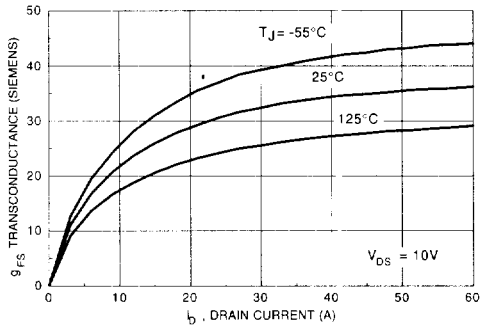

Figure 13. Transconductance Variation with Drain Current and Temperature.

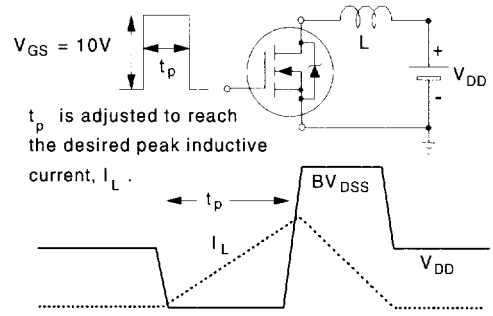

Figure 14. Unclamped Inductive Load Circuit and Waveforms.

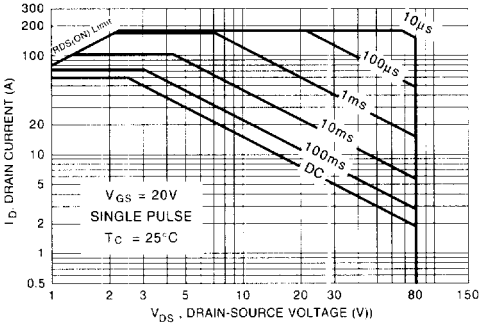

Figure 15. Maximum Safe Operating Area.

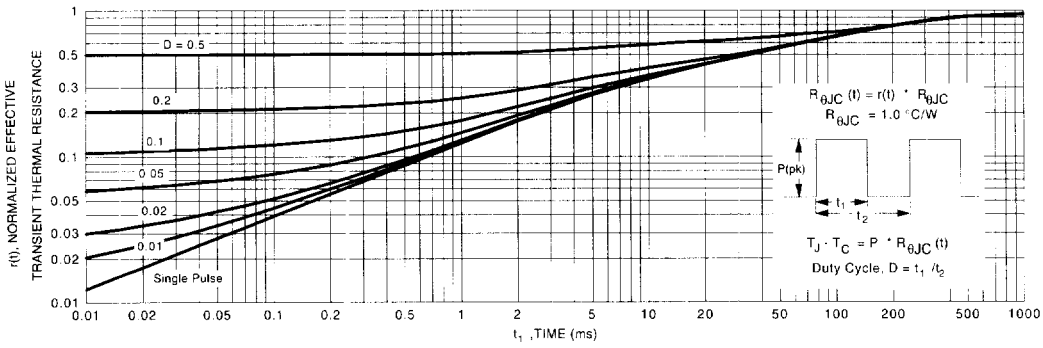

Figure 16. Transient Thermal Response Curve.